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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16ce625-20i-ss

4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (Table 4-1). These registers are static RAM.

The special registers can be classified into two sets (core and peripheral). The Special Function Registers associated with the “core” functions are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

TABLE 4-1: SPECIAL REGISTERS FOR THE PIC16CE62X

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other resets(1)
Bank 0											
00h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
01h	TMR0	Timer0 Module’s Register								xxxx xxxx	uuuu uuuu
02h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h	STATUS	IRP(2)	RP1(2)	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
04h	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	---x 0000	---u 0000
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h	Unimplemented									–	–
08h	Unimplemented									–	–
09h	Unimplemented									–	–
0Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	---0 0000
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0-- ----	-0-- ----
0Dh-1Eh	Unimplemented									–	–
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
Bank 1											
80h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
81h	OPTION	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
83h	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
84h	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
87h	Unimplemented									–	–
88h	Unimplemented									–	–
89h	Unimplemented									–	–
8Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	---0 0000
8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0-- ----	-0-- ----
8Dh	Unimplemented									–	–
8Eh	PCON	—	—	—	—	—	—	$\overline{POR}$	$\overline{BOD}$	---- --0x	---- --uq
8Fh-9Eh	Unimplemented									–	–
90h	EEINTF	—	—	—	—	—	EESCL	EESDA	EEVDD	---- -111	---- -111
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations read as ‘0’, u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: Other (non power-up) resets include $\overline{MCLR}$ reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

Note 2: IRP & RPI bits are reserved; always maintain these bits clear.

FIGURE 5-3: BLOCK DIAGRAM OF RA3 PIN

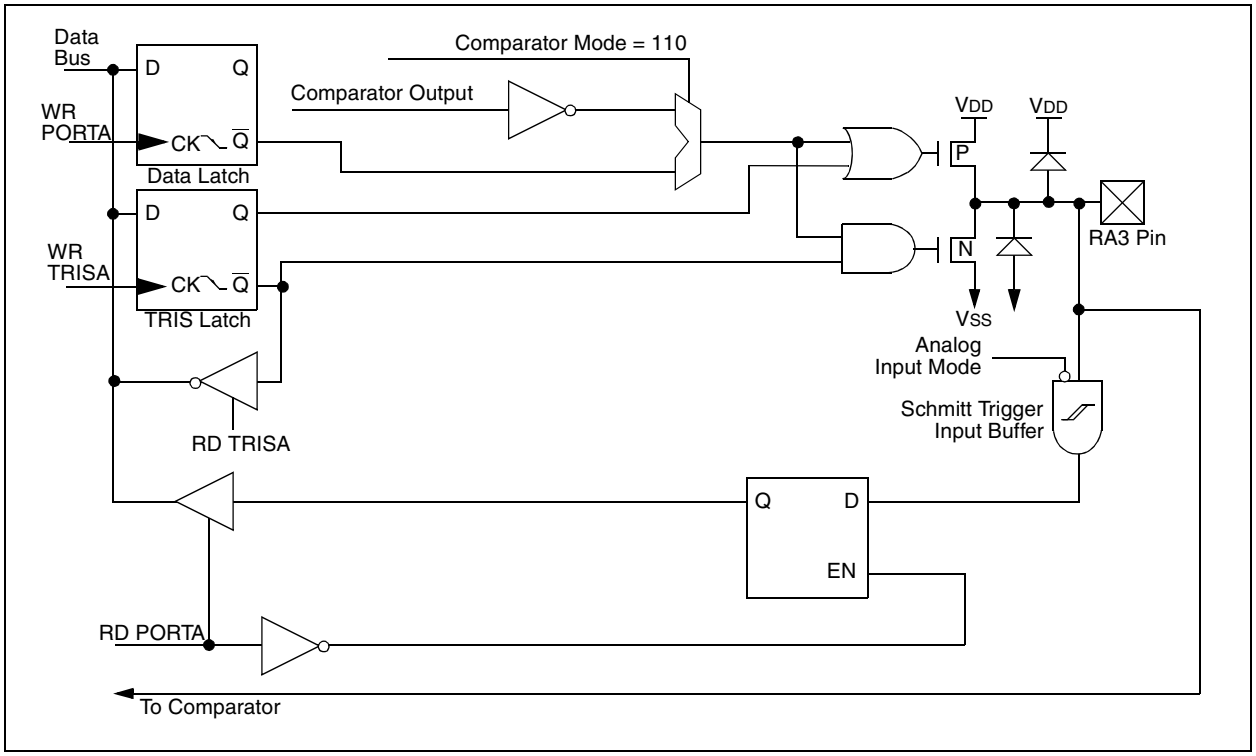
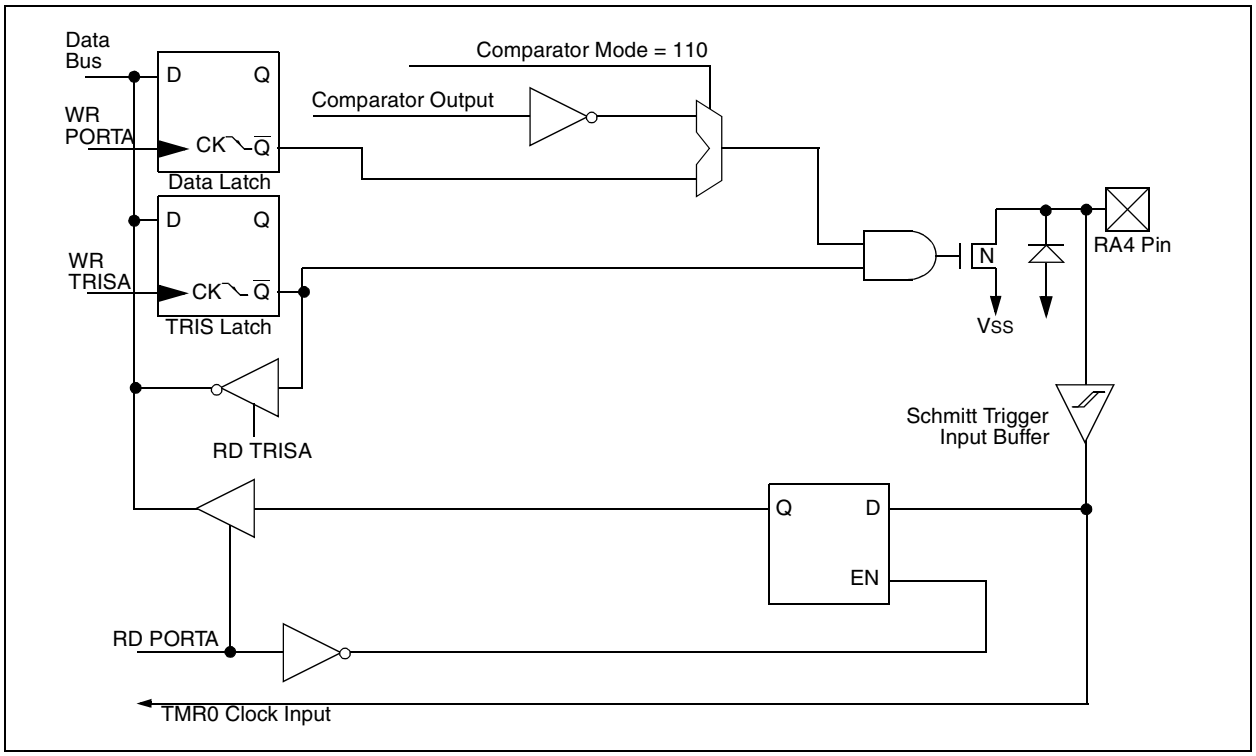


FIGURE 5-4: BLOCK DIAGRAM OF RA4 PIN



5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bidirectional I/O pin (i.e., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read modify write instructions (i.e., BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (i.e., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

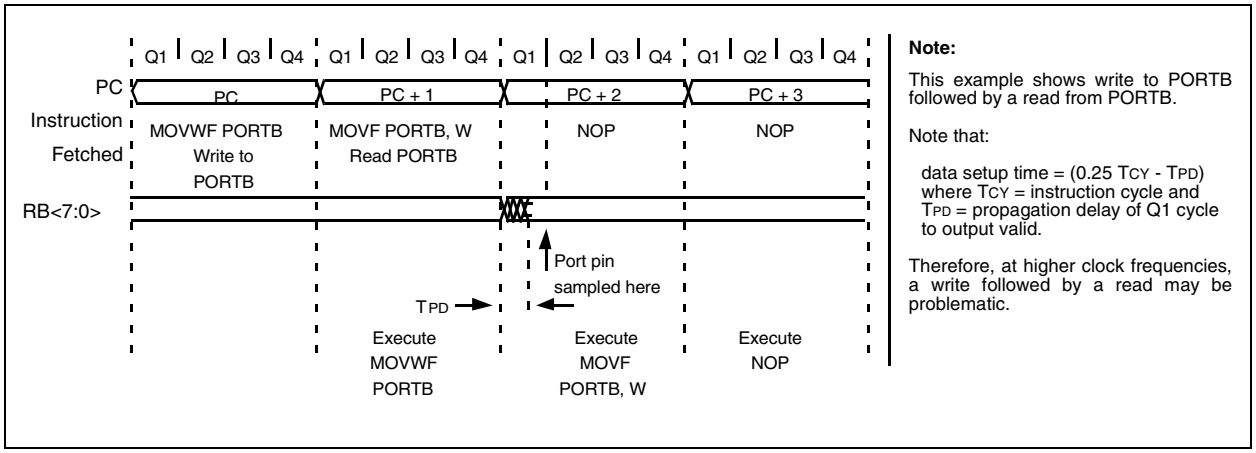
```
; Initial PORT settings:  PORTB<7:4> Inputs
;                         PORTB<3:0> Outputs
; PORTB<7:6> have external pull-up and are not
; connected to other circuitry
;
;                         PORT latch  PORT pins
;                         ----------  ----------

    BCF PORTB, 7        ; 01pp pppp   11pp pppp
    BCF PORTB, 6        ; 10pp pppp   11pp pppp
    BSF STATUS,RP0      ;
    BCF TRISB, 7        ; 10pp pppp   11pp pppp
    BCF TRISB, 6        ; 10pp pppp   10pp pppp
;
; Note that the user may have expected the pin
; values to be 00pp pppp. The 2nd BCF caused
; RB7 to be latched as the pin value (High).
```

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction causes that file to be read into the CPU. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with an NOP or another instruction not accessing this I/O port.

FIGURE 5-7: SUCCESSIVE I/O OPERATION



Note:

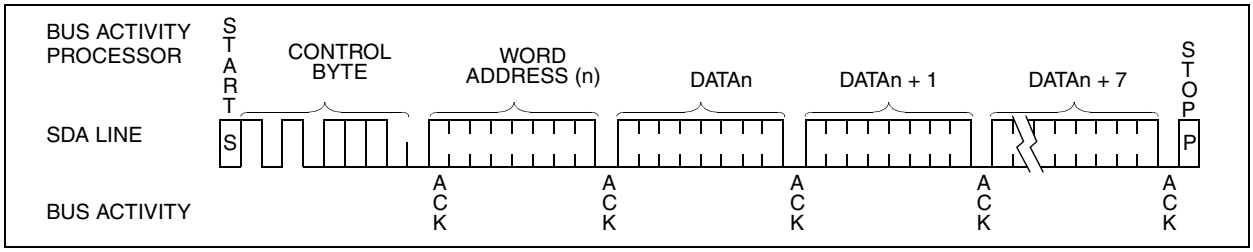
This example shows write to PORTB followed by a read from PORTB.

Note that:

data setup time = (0.25 TCY - TPD) where TCY = instruction cycle and TPD = propagation delay of Q1 cycle to output valid.

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

FIGURE 6-6: PAGE WRITE



6.5 Read Operation

Read operations are initiated in the same way as write operations with the exception that the R/$\overline{W}$ bit of the EEPROM address is set to one. There are three basic types of read operations: current address read, random read, and sequential read.

6.6 Current Address Read

The EEPROM contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous access (either a read or write operation) was to address n, the next current address read operation would access data from address n + 1. Upon receipt of the EEPROM address with R/$\overline{W}$ bit set to one, the EEPROM issues an acknowledge and transmits the eight bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-7).

6.7 Random Read

Random read operations allow the processor to access any memory location in a random manner. To perform this type of read operation, first the word address must be set. This is done by sending the word address to the EEPROM as part of a write operation. After the word address is sent, the processor generates a start condition following the acknowledge. This terminates the write operation, but not before the internal address pointer is set. Then the processor issues the control byte again, but with the R/$\overline{W}$ bit set to a one. The EEPROM will then issue an acknowledge and transmits the eight bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-8).

6.8 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the EEPROM transmits the first data byte, the processor issues an acknowledge as opposed to a stop condition in a random read. This directs the EEPROM to transmit the next sequentially addressed 8-bit word (Figure 6-9).

To provide sequential reads, the EEPROM contains an internal address pointer which is incremented by one at the completion of each operation. This address pointer allows the entire memory contents to be serially read during one operation.

6.9 Noise Protection

The EEPROM employs a VCC threshold detector circuit, which disables the internal erase/write logic if the VCC is below 1.5 volts at nominal conditions.

The SCL and SDA inputs have Schmitt trigger and filter circuits, which suppress noise spikes to assure proper device operation even on a noisy bus.

FIGURE 7-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

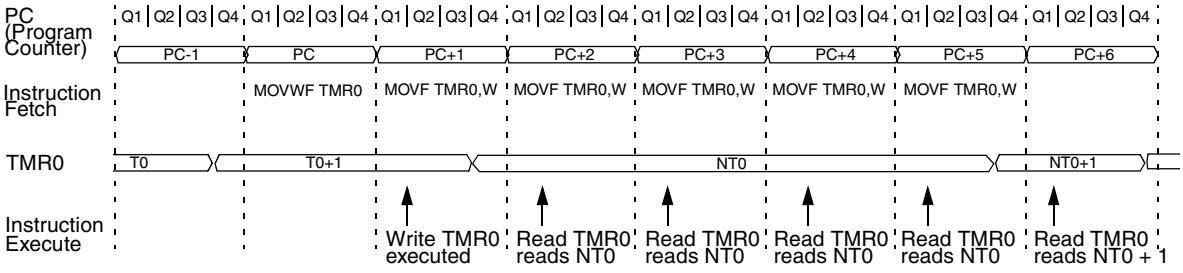
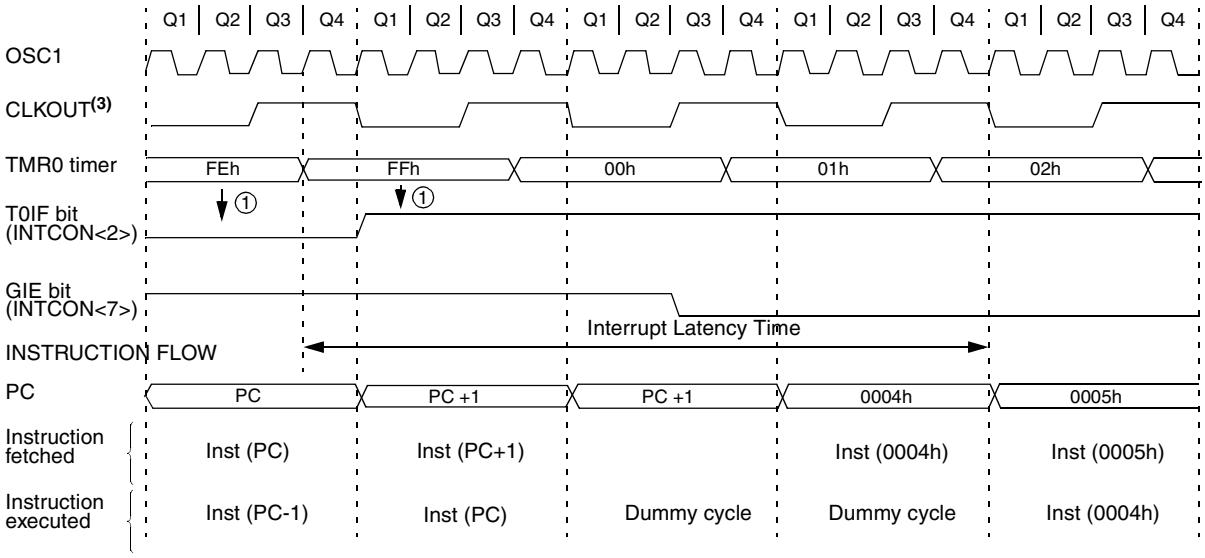


FIGURE 7-4: TIMER0 INTERRUPT TIMING



Note 1: T0IF interrupt flag is sampled here (every Q1).
2: Interrupt latency = 3TCY, where TCY = instruction cycle time.
3: CLKOUT is available only in RC oscillator mode.

8.4 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output has a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs, otherwise the maximum delay of the comparators should be used (Table 13-1 **).**

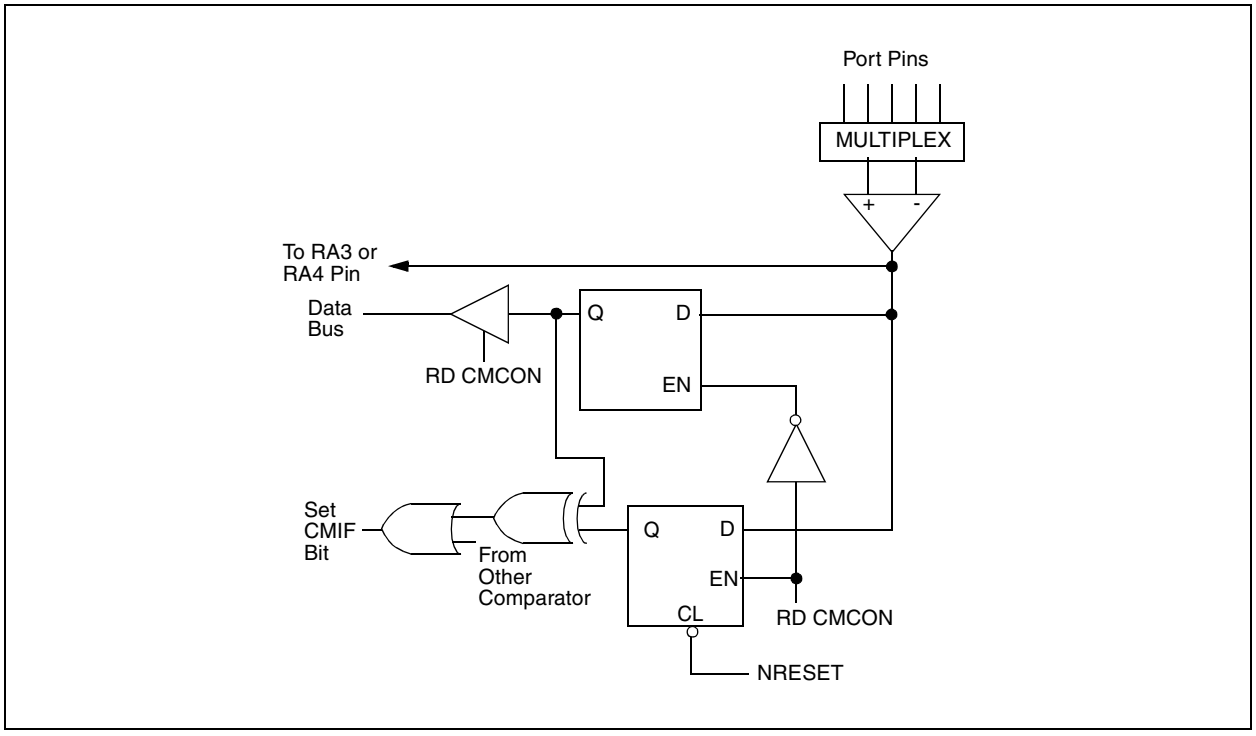
8.5 Comparator Outputs

The comparator outputs are read through the CMCON register. These bits are read only. The comparator outputs may also be directly output to the RA3 and RA4 I/O pins. When the CM<2:0> = 110, multiplexors in the output path of the RA3 and RA4 pins will switch and the output of each pin will be the unsynchronized output of the comparator. The uncertainty of each of the comparators is related to the input offset voltage and the response time given in the specifications. Figure 8-3 shows the comparator output block diagram.

The TRISA bits will still function as an output enable/disable for the RA3 and RA4 pins while in this mode.

Note 1:	When reading the PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert an analog input according to the Schmitt Trigger input specification.
2:	Analog levels on any pin that is defined as a digital input may cause the input buffer to consume more current than is specified.

FIGURE 8-3: COMPARATOR OUTPUT BLOCK DIAGRAM



EXAMPLE 9-1: VOLTAGE REFERENCE CONFIGURATION

```
MOVLW     0x02          ; 4 Inputs Muxed
MOVWF     CMCON         ; to 2 comps.
BSF       STATUS,RP0    ; go to Bank 1
MOVLW     0x07          ; RA3-RA0 are
MOVWF     TRISA         ; outputs
MOVLW     0xA6          ; enable VREF
MOVWF     VRCON         ; low range
                        ; set VR<3:0>=6
BCF       STATUS,RP0    ; go to Bank 0
CALL      DELAY10       ; 10µs delay
```

9.2 Voltage Reference Accuracy/Error

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 9-1) keep VREF from approaching VSS or VDD. The Voltage Reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The absolute accuracy of the Voltage Reference can be found in Table 13-2.

9.3 Operation During Sleep

When the device wakes up from sleep through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the Voltage Reference should be disabled.

9.4 Effects of a Reset

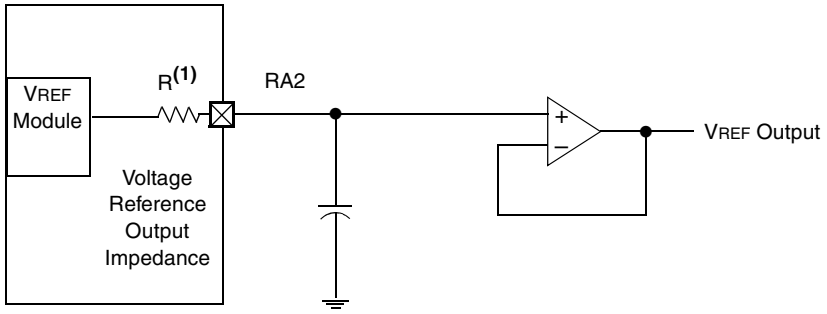
A device reset disables the Voltage Reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

9.5 Connection Considerations

The Voltage Reference Module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the Voltage Reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the Voltage Reference output for external connections to VREF. Figure 9-2 shows an example buffering technique.

FIGURE 9-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



Note 1: R is dependent upon the Voltage Reference Configuration VRCON<3:0> and VRCON<5>.

TABLE 9-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR / BOD	Value On All Other Resets
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: - = Unimplemented, read as "0"

10.4.5 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: First PWRT time-out is invoked after POR has expired, then OST is activated. The total time-out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in RC mode with $\overline{\text{PWRTE}}$ bit erased (PWRT disabled), there will be no time-out at all. Figure 10-8, Figure 10-9 and Figure 10-10 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 10-9). This is useful for testing purposes or to synchronize more than one PIC® device operating in parallel.

Table 10-5 shows the reset conditions for some special registers, while Table 10-6 shows the reset conditions for all the registers.

10.4.6 POWER CONTROL (PCON)/STATUS REGISTER

The power control/status register, PCON (address 8Eh) has two bits.

Bit0 is $\overline{\text{BOR}}$ (Brown-out). $\overline{\text{BOR}}$ is unknown on power-on-reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOR}}$ = 0 indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by setting BODEN bit = 0 in the Configuration word).

Bit1 is $\overline{\text{POR}}$ (Power-on-reset). It is a '0' on power-on-reset and unaffected otherwise. The user must write a '1' to this bit following a power-on-reset. On a subsequent reset, if $\overline{\text{POR}}$ is '0', it will indicate that a power-on-reset must have occurred (V_{DD} may have gone too low).

TABLE 10-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset	Wake-up from SLEEP
	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1		
XT, HS, LP	72 ms + 1024 TOSC	1024 TOSC	72 ms + 1024 TOSC	1024 TOSC
RC	72 ms	—	72 ms	—

TABLE 10-4: STATUS/PCON BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	
0	x	1	1	Power-on-reset
0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	x	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
1	0	x	x	Brown-out Reset
1	1	0	u	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{\text{MCLR}}$ reset during normal operation
1	1	1	0	$\overline{\text{MCLR}}$ reset during SLEEP

Legend: x = unknown, u = unchanged

TABLE 11-2: PIC16CE62X INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS						
ADDWF	**f, d**	Add W and f	1	00 0111 dfff ffff	C,DC,Z	1,2
ANDWF	**f, d**	AND W with f	1	00 0101 dfff ffff	Z	1,2
CLRF	**f**	Clear f	1	00 0001 lfff ffff	Z	2
CLRW	**-**	Clear W	1	00 0001 0000 0011	Z	
COMF	**f, d**	Complement f	1	00 1001 dfff ffff	Z	1,2
DECF	**f, d**	Decrement f	1	00 0011 dfff ffff	Z	1,2
DECFSZ	**f, d**	Decrement f, Skip if 0	1(2)	00 1011 dfff ffff		1,2,3
INCF	**f, d**	Increment f	1	00 1010 dfff ffff	Z	1,2
INCFSZ	**f, d**	Increment f, Skip if 0	1(2)	00 1111 dfff ffff		1,2,3
IORWF	**f, d**	Inclusive OR W with f	1	00 0100 dfff ffff	Z	1,2
MOVF	**f, d**	Move f	1	00 1000 dfff ffff	Z	1,2
MOVWF	**f**	Move W to f	1	00 0000 lfff ffff		
NOP	**-**	No Operation	1	00 0000 0xx0 0000		
RLF	**f, d**	Rotate Left f through Carry	1	00 1101 dfff ffff	C	1,2
RRF	**f, d**	Rotate Right f through Carry	1	00 1100 dfff ffff	C	1,2
SUBWF	**f, d**	Subtract W from f	1	00 0010 dfff ffff	C,DC,Z	1,2
SWAPF	**f, d**	Swap nibbles in f	1	00 1110 dfff ffff		1,2
XORWF	**f, d**	Exclusive OR W with f	1	00 0110 dfff ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS						
BCF	**f, b**	Bit Clear f	1	01 00bb bfff ffff		1,2
BSF	**f, b**	Bit Set f	1	01 01bb bfff ffff		1,2
BTFSC	**f, b**	Bit Test f, Skip if Clear	1 (2)	01 10bb bfff ffff		3
BTFSS	**f, b**	Bit Test f, Skip if Set	1 (2)	01 11bb bfff ffff		3
LITERAL AND CONTROL OPERATIONS						
ADDLW	**k**	Add literal and W	1	11 111x kkkk kkkk	C,DC,Z	
ANDLW	**k**	AND literal with W	1	11 1001 kkkk kkkk	Z	
CALL	**k**	Call subroutine	2	10 0kkk kkkk kkkk		
CLRWDT	**-**	Clear Watchdog Timer	1	00 0000 0110 0100	$\overline{TO}$,$\overline{PD}$	
GOTO	**k**	Go to address	2	10 1kkk kkkk kkkk		
IORLW	**k**	Inclusive OR literal with W	1	11 1000 kkkk kkkk	Z	
MOVLW	**k**	Move literal to W	1	11 00xx kkkk kkkk		
RETFIE	**-**	Return from interrupt	2	00 0000 0000 1001		
RETLW	**k**	Return with literal in W	2	11 01xx kkkk kkkk		
RETURN	**-**	Return from Subroutine	2	00 0000 0000 1000		
SLEEP	**-**	Go into standby mode	1	00 0000 0110 0011	$\overline{TO}$,$\overline{PD}$	
SUBLW	**k**	Subtract W from literal	1	11 110x kkkk kkkk	C,DC,Z	
XORLW	**k**	Exclusive OR literal with W	1	11 1010 kkkk kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

11.1 Instruction Descriptions

ADDLW **Add Literal and W**

Syntax: [*label*] ADDLW k

Operands: $0 \le k \le 255$

Operation: (W) + k → (W)

Status Affected: C, DC, Z

Encoding:

11	111x	kkkk	kkkk

Description: The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.

Words: 1

Cycles: 1

Example
```
ADDLW   0x15
```
Before Instruction
W = 0x10
After Instruction
W = 0x25

ANDLW **AND Literal with W**

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. (k) → (W)

Status Affected: Z

Encoding:

11	1001	kkkk	kkkk

Description: The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example
```
ANDLW   0x5F
```
Before Instruction
W = 0xA3
After Instruction
W = 0x03

ADDWF **Add W and f**

Syntax: [*label*] ADDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) + (f) → (dest)

Status Affected: C, DC, Z

Encoding:

00	0111	dfff	ffff

Description: Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
ADDWF   FSR, 0
```
Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0xD9
FSR = 0xC2

ANDWF **AND W with f**

Syntax: [*label*] ANDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .AND. (f) → (dest)

Status Affected: Z

Encoding:

00	0101	dfff	ffff

Description: AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
ANDWF   FSR, 1
```
Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0x17
FSR = 0x02

BTFSS **Bit Test f, Skip if Set**

Syntax: [*label*] BTFSS f,b

Operands: 0 ≤ f ≤ 127
0 ≤ b < 7

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

01	11bb	bfff	ffff

Description: If bit 'b' in register 'f' is '1' then the next instruction is skipped.
If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```
HERE    BTFSS  FLAG,1
FALSE   GOTO   PROCESS_CODE
TRUE    •
        •
        •
```

Before Instruction
PC = address HERE
After Instruction
if FLAG<1> = 0,
PC = address FALSE
if FLAG<1> = 1,
PC = address TRUE

CALL **Call Subroutine**

Syntax: [*label*] CALL k

Operands: 0 ≤ k ≤ 2047

Operation: (PC)+ 1→ TOS,
k → PC<10:0>,
(PCLATH<4:3>) → PC<12:11>

Status Affected: None

Encoding:

10	0kkk	kkkk	kkkk

Description: Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
HERE    CALL   THERE
```

Before Instruction
PC = Address HERE
After Instruction
PC = Address THERE
TOS = Address HERE+1

CLRF **Clear f**

Syntax: [*label*] CLRF f

Operands: 0 ≤ f ≤ 127

Operation: 00h → (f)
1 → Z

Status Affected: Z

Encoding:

00	0001	1fff	ffff

Description: The contents of register 'f' are cleared and the Z bit is set.

Words: 1

Cycles: 1

Example

```
CLRF    FLAG_REG
```

Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Encoding:

00	0001	0000	0011

Description: W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example

```
CLRW
```

Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

NOP — **No Operation**

Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Encoding:	00 | 0000 | 0xx0 | 0000
Description:	No operation.
Words:	1
Cycles:	1
Example	NOP

OPTION — **Load Option Register**

Syntax:	[*label*] OPTION
Operands:	None
Operation:	(W) → OPTION
Status Affected:	None
Encoding:	00 | 0000 | 0110 | 0010
Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.
Words:	1
Cycles:	1
Example	

To maintain upward compatibility with future PIC® MCU products, do not use this instruction.

RETFIE — **Return from Interrupt**

Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None
Encoding:	00 | 0000 | 0000 | 1001
Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction.
Words:	1
Cycles:	2
Example	RETFIE After Interrupt PC = TOS GIE = 1

RETLW — **Return with Literal in W**

Syntax:	[*label*] RETLW k
Operands:	0 ≤ k ≤ 255
Operation:	k → (W); TOS → PC
Status Affected:	None
Encoding:	11 | 01xx | kkkk | kkkk
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2
Example	

```
        CALL TABLE      ;W contains table
                        ;offset value
        •               ;W now has table
        value
        •
TABLE   •
        ADDWF PC        ;W = offset
        RETLW k1        ;Begin table
        RETLW k2        ;
        •
        •
        •
        RETLW kn        ; End of table
```

Before Instruction
W = 0x07
After Instruction
W = value of k8

and test the sample code. In addition, PICDEM-17 supports down-loading of programs to and executing out of external FLASH memory on board. The PICDEM-17 is also usable with the MPLAB-ICE or PICMASTER emulator, and all of the sample programs can be run and modified using either emulator. Additionally, a generous prototype area is available for user hardware.

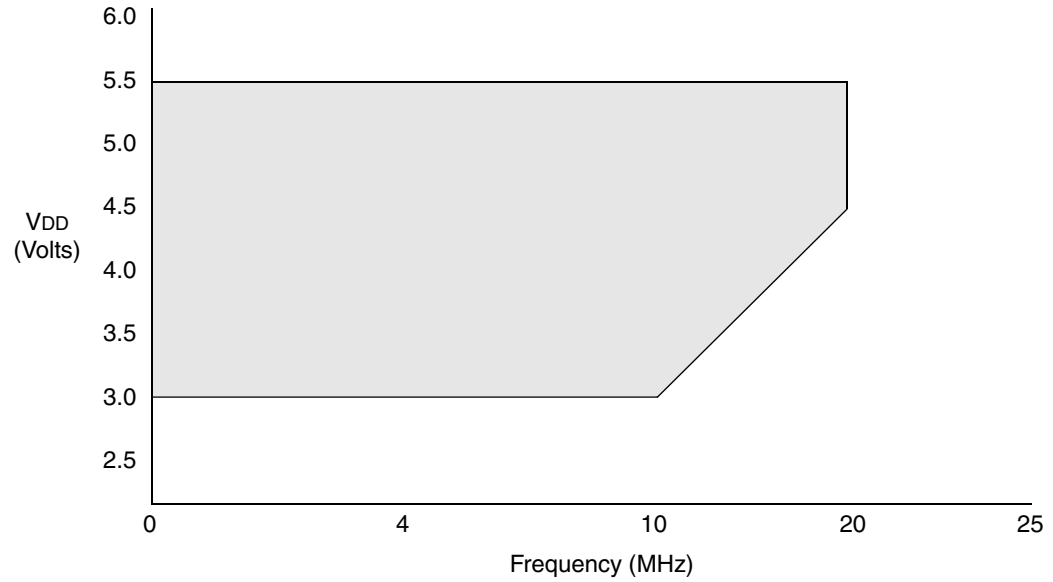
12.17 SEEVAL Evaluation and Programming System

The SEEVAL SEEPROM Designer's Kit supports all Microchip 2-wire and 3-wire Serial EEPROMs. The kit includes everything necessary to read, write, erase or program special features of any Microchip SEEPROM product including Smart Serials™ and secure serials. The Total Endurance™ Disk is included to aid in trade-off analysis and reliability calculations. The total kit can significantly reduce time-to-market and result in an optimized system.

12.18 KEELOQ Evaluation and Programming Tools

KEELOQ evaluation and programming tools support Microchips HCS Secure Data Products. The HCS evaluation kit includes an LCD display to show changing codes, a decoder to decode transmissions, and a programming interface to program test transmitters.

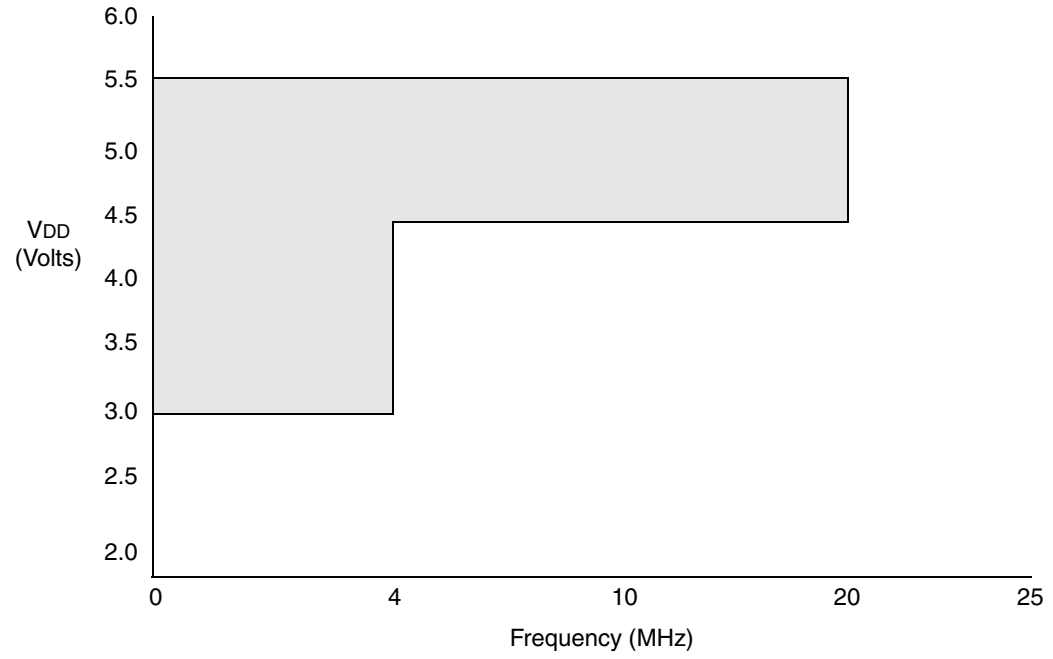
FIGURE 13-1: PIC16CE62X VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

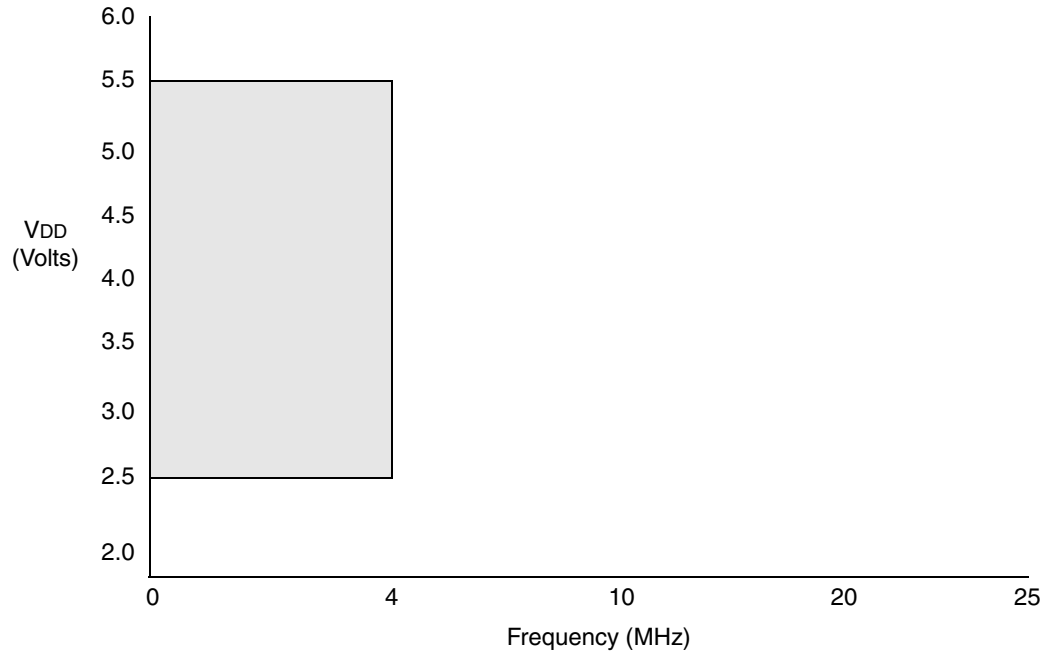
FIGURE 13-2: PIC16CE62X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA < 0°C, +70°C < TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 13-3: PIC16LCE62X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA < +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

13.2 DC CHARACTERISTICS: PIC16LCE62X-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	2.5	–	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	–	1.5*	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	–	VSS	–	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	.05*	–	–	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2)	–	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*
			–	–	1.1	mA	FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT osc mode, (Note 4)
			–	35	70	µA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	–	–	2.0	µA	VDD = 2.5V
			–	–	2.2	µA	VDD = 3.0V*
			–	–	9.0	µA	VDD = 5.5V
			–	–	15	µA	VDD = 5.5V Extended
D022	ΔIWDT	WDT Current (Note 5)	–	6.0	10	µA	VDD=4.0V
					12	µA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current (Note 5)	–	75	125	µA	$\overline{BOD}$ enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator (Note 5)	–	30	60	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current (Note 5)	–	80	135	µA	VDD = 4.0V
	ΔIEE Write	Operating Current	–		3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔIEE Read	Operating Current	–		1	mA	
	ΔIEE	Standby Current	–		30	µA	VCC = 3.0V, EE VDD = VCC
	ΔIEE	Standby Current	–		100	µA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

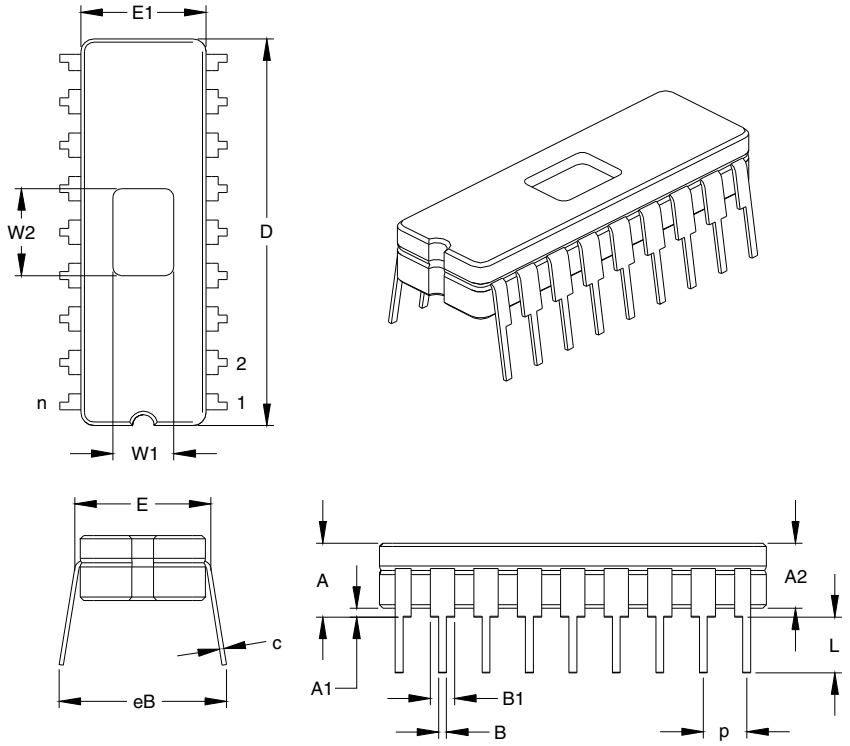
5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

14.0 PACKAGING INFORMATION

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

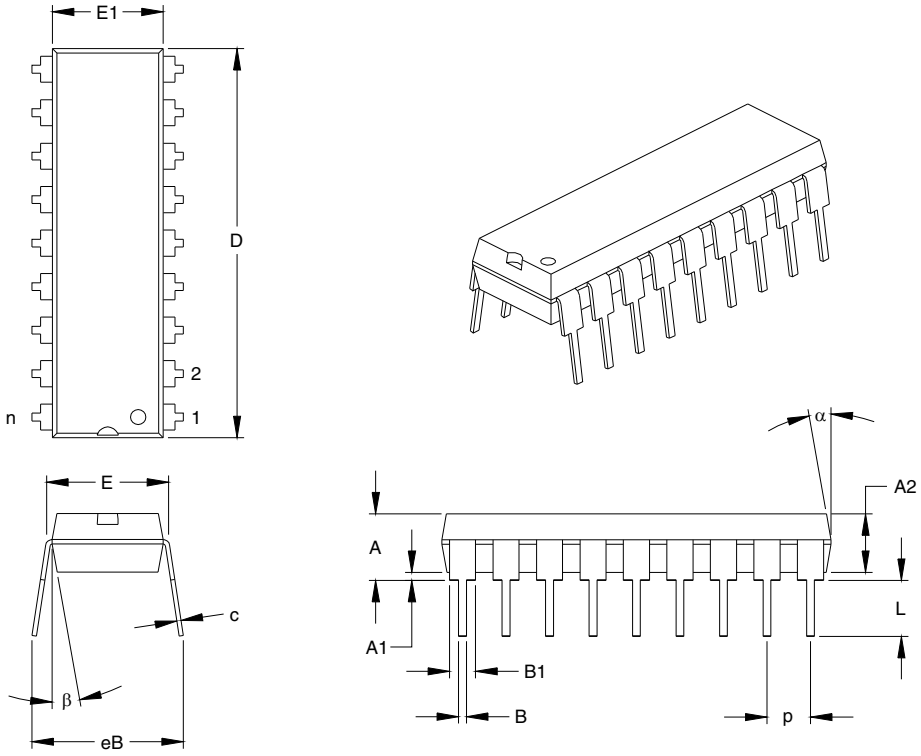


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

*Controlling Parameter
JEDEC Equivalent: MO-036
Drawing No. C04-010

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-007

APPENDIX A: CODE FOR ACCESSING EEPROM DATA MEMORY

Please check our web site at www.microchip.com for code availability.

APPENDIX B:REVISION HISTORY

Revision D (January 2013)

Added a note to each package outline drawing.

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

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Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.